

Switch, N-Channel MMBF4117

Description

This device is designed for low current DC and audio applications. These devices provide excellent performance as input stages for sub-picoamp instrumentation or any high impedance signal sources. Sourced from process 53.

ABSOLUTE MAXIMUM RATINGS

Values are at $T_A = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Value	Unit
V_{DG}	Drain-Gate Voltage	40	٧
V_{GS}	Gate-Source Voltage	-40	V
I _{GF}	Forward Gate Current	50	mA
T _J , T _{STG}	Operating and Storage Temperature Range	–55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. These ratings are based on a maximum junction temperature of 150°C.
- These are steady-state limits. onsemi should be consulted on applications involving pulsed or low-duty-cycle operations.

THERMAL CHARACTERISTICS

Values are at $T_A = 25^{\circ}C$ unless otherwise noted.

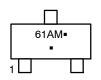
Symbol	Parameter	Value	Unit
P_{D}	Total Device Dissipation	225	mW
·	Derate Above 25°C	1.8	mW/°C
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	556	°C/W

3. Device mounted on FR-4 PCB 1.6 inch x 1.6 inch x 0.06 inch.

SOT-23 (TO-236) CASE 318-08

Note: Source & Drain are interchangeable.

MARKING DIAGRAM



61A = Specific Device Code

M = Date Code

= Pb – Free Package

ORDERING INFORMATION

Device	Package	Shipping [†]	
MMBF4117	SOT-23 3L	3000 /	
		Tape & Reel	

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS Values are at T_A = 25°C unless otherwise noted.

Symbol	Parameter Conditions		Min	Max	Unit
OFF CHAR	ACTERISTICS	•	-		
V _{(BR)GSS}	Gate-Source Breakdown Voltage	$I_G = -1.0 \mu A, V_{DS} = 0$	-40	-	V
I _{GSS}	Gate Reverse Current	V _{GS} = -20 V, V _{DS} = 0	-	-10	pА
		$V_{GS} = -20 \text{ V}, V_{DS} = 0, T_A = 150^{\circ}\text{C}$	_	-25	nA
V _{GS(off)}	Gate-Source Cut-Off Voltage	V _{DS} = -10 V, I _D = 1.0 nA	-0.6	-1.8	V
ON CHARA	ACTERISTICS				
I _{DSS}	Zero-Gate Voltage Drain Current	V _{DS} = 10 V, V _{GS} = 0	30	90	μΑ
SMALL SIG	GNAL CHARACTERISTICS				
9fs	Common Source Forward Transconductance	V _{DS} = 10 V, V _{GS} = 0, f = 1.0 kHz	70	210	μmhos
g _{oss}	Common-Source Output Conductance	V _{DS} = 10 V, V _{GS} = 0, f = 1.0 kHz	_	3.0	μmhos
R _{e(yfs)}	Common-Source Forward Transconductance	V _{DS} = 10 V, V _{GS} = 0, f = 30 MHz	60	-	μmhos
C _{iss}	Input Capacitance	V _{DS} = 10 V, V _{GS} = 0, f = 1.0 kHz	_	3.0	pF
C _{rss}	Reverse Transfer Capacitance	V _{DS} = 10 V, V _{GS} = 0, f = 1.0 MHz	-	1.5	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

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4. Pulse test: pulse width ≤ 300 μs, duty cycle ≤ 1.0%.

MMBF4117

TYPICAL CHARACTERISTICS

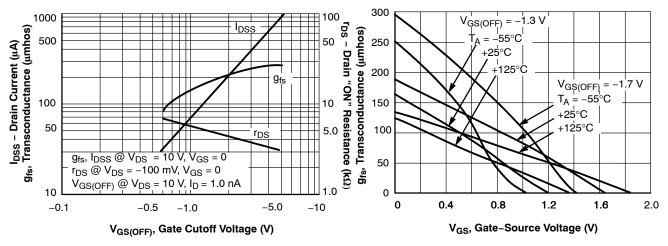


Figure 1. Parameter Interactions

Figure 2. Transfer Characteristics

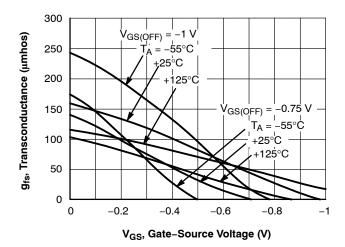


Figure 3. Transfer Characteristics

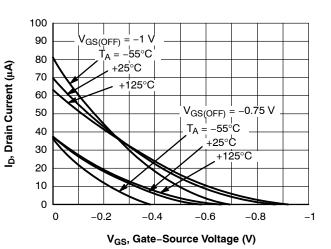


Figure 4. Transfer Characteristics

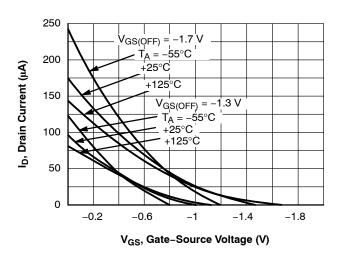


Figure 5. Transfer Characteristics

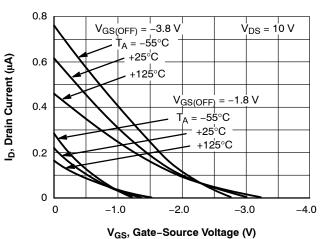


Figure 6. Transfer Characteristics

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TYPICAL CHARACTERISTICS (Continued)

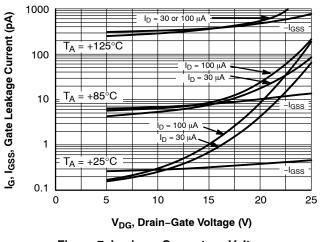


Figure 7. Leakage Current vs. Voltage

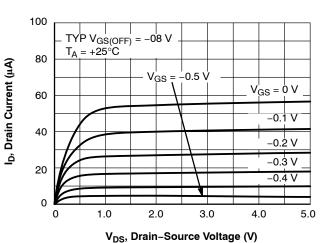


Figure 8. Common Drain-Source

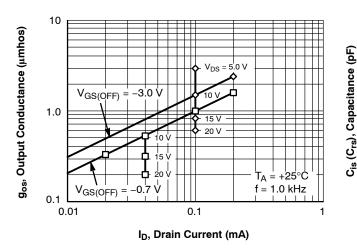


Figure 9. Output Conductance vs. Drain Current

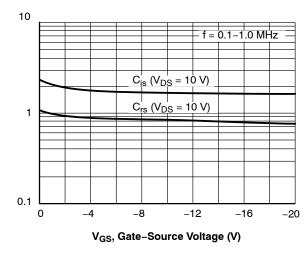


Figure 10. Capacitance vs. Voltage

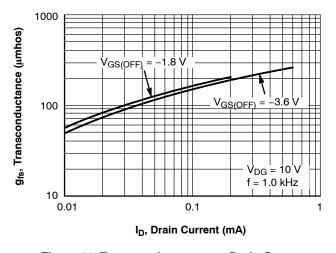


Figure 11. Transconductance vs. Drain Current

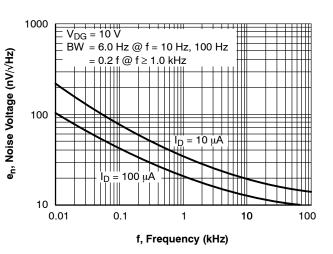


Figure 12. Noise Voltage vs. Frequency

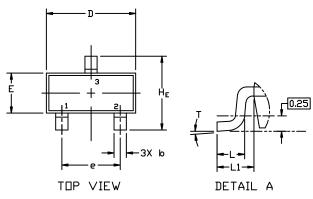


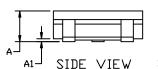


SOT-23 (TO-236) CASE 318 ISSUE AT

DATE 01 MAR 2023









NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS		INCHES			
DIM	MIN.	N□M.	MAX.	MIN.	N□M.	MAX.
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
С	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
Ε	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
Т	0*		10°	0*		10°

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

M = Date Code

■ = Pb-Free Package



RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

STYLES ON PAGE 2

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^{*}This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



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STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 7: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 8: PIN 1. ANODE 2. NO CONNECTION 3. CATHODE	1	
STYLE 9:	STYLE 10:	STYLE 11:	STYLE 12: PIN 1. CATHODE 2. CATHODE 3. ANODE	STYLE 13:	STYLE 14:
PIN 1. ANODE	PIN 1. DRAIN	PIN 1. ANODE		PIN 1. SOURCE	PIN 1. CATHODE
2. ANODE	2. SOURCE	2. CATHODE		2. DRAIN	2. GATE
3. CATHODE	3. GATE	3. CATHODE-ANODE		3. GATE	3. ANODE
STYLE 15:	STYLE 16:	STYLE 17:	STYLE 18:	STYLE 19:	STYLE 20:
PIN 1. GATE	PIN 1. ANODE	PIN 1. NO CONNECTION	PIN 1. NO CONNECTION	N PIN 1. CATHODE	PIN 1. CATHODE
2. CATHODE	2. CATHODE	2. ANODE	2. CATHODE	2. ANODE	2. ANODE
3. ANODE	3. CATHODE	3. CATHODE	3. ANODE	3. CATHODE-ANODE	3. GATE
STYLE 21:	STYLE 22:	STYLE 23:	STYLE 24:	STYLE 25:	STYLE 26:
PIN 1. GATE	PIN 1. RETURN	PIN 1. ANODE	PIN 1. GATE	PIN 1. ANODE	PIN 1. CATHODE
2. SOURCE	2. OUTPUT	2. ANODE	2. DRAIN	2. CATHODE	2. ANODE
3. DRAIN	3. INPUT	3. CATHODE	3. SOURCE	3. GATE	3. NO CONNECTION
STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE				

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